

SLC/BLC

Leading in Vapor Phase Technology

Premium Vapor Phase Soldering Series For Highest Demands

IBL



The Machine

The SLC/BLC reflow vapor phase soldering systems (available as batch or inline) are perfect for medium to high volume production. The machines offer highest quality performances with smallest footprints. Many patented features are available and provide a wide range of flexibility

Overview

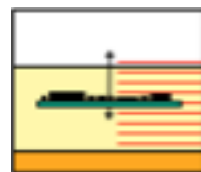
- 11 machine types for different board sizes
- Small footprint
- 2-chamber design
- Oxygen free soldering
- No overheating of components
- Low power consumption

Standard Equipment / Specification

- Comfortable operation with Touch Screen
- Automatic carrier in- and output
- Program memory up to 50 programs
- Wide variety of adjustable solder profiles
- Low fluid consumption with 2-chamber design and fluid recovery
- Integrated cooling fan for board cooling
- Minimum maintenance and wear due to „cool handling“ (all moving parts outside the process chamber)
- 4 internal channels for comfortable temperature measuring and profiling
- Energy management system
- Fluid level check
- Automatic liquid filtering
- Integrated illumination of the soldering area

Special features

- IPS, Intelligent Profiling System incl.
 - Soft Vapor Temperature Control (SVTC), temperature regulated profiles
 - Pilot Mode, set-up and profiling in one step
- Lead-free and leaded soldering with one fluid only, with different maximum temperatures
- Built-in software profiling capability
- Syncro-Mode
- Maintenance-free transport system (patented)
- Easy access to process chamber



Easily programmable vapor steps allow optimum adjustments of gradients

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Options

- RCS Rapid Cooling System (**patented**)
- IR heater system (**patented**)
- VP-Control for convenient documentation and fine adjustment of the process
- Integrated PC-System
- Barcode-system for automatic program-change, traceability and unlimited program storage
- Measurement channels for board temperature recording
- Multi-Level-Mode for easy changeover between different solder heights
- Anti Fog System (AFS) for clear vision of the soldering process (**patented**)
- Adapter for double sided PCB boards
- UPS, uninterruptible power supply
- Inline-handling
- Closed-loop-chiller



Technical Data	SLC309	SLC509	SLC609	SLC809	BLC509	BLC609	BLC809
Length (over all)	940 mm	1190 mm	1290 mm	1490 mm	1190 mm	1290 mm	1490 mm
Depth	1760 mm	1760 mm	1760 mm	1760 mm	1960 mm	1960 m	1960 mm
Height	1320 mm	1320 mm	1320 mm	1320 mm	1320 mm	1320 mm	1320 mm
Weight	415 kg	500 kg	550 kg	600 kg	560 kg	650 kg	700 kg
Loading/unloading level, approx.	950 mm						
Max. board size Batch (in mm)	300 x 350 x 80	550 x 350 x 80	650 x 350 x 80	850 x 350 x 80	550 x 540 x 80	650 x 540 x 80	850 x 540 x 80
Max. board size Inline (in mm)	N/A	540 x 307 x 50	640 x 307 x 50	840 x 307 x 50	540 x 400 x 50	640 x 400 x 50	840 x 400 x 50
Liquid agent filling	10 kg	15 kg	15 kg	20 kg	20 kg	20 kg	25kg
Water connection	1/2" / 2,5-5 bar						
	1,5l/min	2,5l/min	3l/min	3,5l/min	3l/min	3l/min	3,5l/min
Max. heating capacity of Vapor Phase heater	3,9 kW	5,2 kW	6,5 kW	7,8 kW	7,8 kW	7,8 kW	9,1 kW
Ø power consumption	1,6 kW/h	2,1 kW/h	2,6 kW/h	3,1 kW/h	3,1 kW/h	3,2 kW/h	3,6 kW/h
Power supply	400 / 230 VAC						
Main fuse	20A "gl" oder "C"			25A "gl" oder "C"			

- Technical changes reserved -

D1E124-Datasheet SLC-BLC E-130711.doc